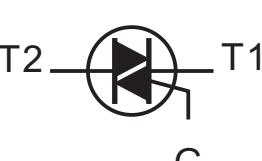
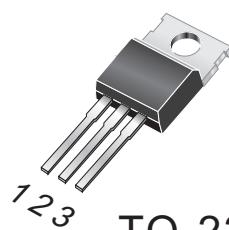


HAOPIN MICROELECTRONICS CO., LTD.

Description

Passivated, sensitive gate triacs in a plastic envelope, intended for use in general purpose bidirectional switching and phase control applications, where high sensitivity is required in all four quadrants.

| Symbol | | Simplified outline |
|---|----------------------|--|
|  | |  TO-220 |
| Pin | Description | |
| 1 | Main terminal 1 (T1) | |
| 2 | Main terminal 2 (T2) | |
| 3 | gate (G) | |
| TAB | Main terminal 2 (T2) | |

Applications:

- ◆ Motor control
- ◆ Industrial and domestic lighting
- ◆ Heating
- ◆ Static switching

Features

- ◆ Blocking voltage to 600 V
- ◆ On-state RMS current to 12 A

| SYMBOL | PARAMETER | Value | Unit |
|-------------|--------------------------------------|-------|------|
| V_{DRM} | Repetitive peak off-state voltages | 600 | V |
| I_T (RMS) | RMS on-state current | 12 | A |
| I_{TSM} | Non-repetitive peak on-state current | 95 | A |

| SYMBOL | PARAMETER | CONDITIONS | MIN | TYP | MAX | UNIT |
|--------------|---|-------------|-----|-----|-----|------|
| R_{thj-mb} | Thermal resistance Junction to mounting base | Full cycle | — | — | 1.5 | K/W |
| | | Half cycle | — | — | 2.0 | K/W |
| R_{thj-a} | Thermal resistance Junction to ambient | In free air | — | 60 | — | K/W |



HP12T60RS

Sensitive Gate Triacs

HAOPIN MICROELECTRONICS CO., LTD.

Limiting values in accordance with the Maximum system(IEC 134)

| SYMBOL | PARAMETER | CONDITIONS | MIN | Value | UNIT | |
|--------------|--|---|------------|-------|------------|-----------|
| V_{DRM} | Repetitive peak off-state Voltages | | - | 600 | V | |
| $I_{T(RMS)}$ | RMS on-state current | Full sine wave; $T_{mb} \leq 99^\circ C$ | - | 12 | A | |
| I_{TSM} | Non-repetitive surge peak on-state current | full sine wave; $T_j=25^\circ C$ prior to surge | $t=20ms$ | - | 95 | A |
| | | | $t=16.7ms$ | - | 105 | A |
| I^2t | I^2t for fusing | $T=10ms$ | - | 45 | A^2s | |
| dI_T/dt | Repetitive rate of rise of on-state current after triggering | $I_{TM}=20A; I_G=0.2A;$ $dI_G/dt=0.2A/\mu s$ | $T2+G+$ | - | 50 | $A/\mu s$ |
| | | | $T2+G-$ | - | 50 | $A/\mu s$ |
| | | | $T2-G-$ | - | 50 | $A/\mu s$ |
| | | | $T2-G+$ | - | 10 | $A/\mu s$ |
| | | | | | | |
| I_{GM} | Peak gate current | | - | 2 | A | |
| V_{GM} | Peak gate voltage | | - | 5 | V | |
| P_{GM} | Peak gate power | | - | 5 | W | |
| $P_{G(AV)}$ | Average gate power | Over any 20 ms period | - | 0.5 | W | |
| T_{stg} | Storage temperature | | -40 | 150 | $^\circ C$ | |
| T_j | Operating junction Temperature | | - | 125 | $^\circ C$ | |

 $T_j=25^\circ C$ unless otherwise stated

| SYMBOL | PARAMETER | CONDITIONS | MIN | TYP | MAX | UNIT | |
|------------------------|---------------------------|---------------------------------------|--|------------------|-------------------------|----------------------|----------------------|
| Static characteristics | | | | | | | |
| I_{GT} | Gate trigger current | $V_D=12V; I_T=0.1A$ | $T2+G+$ $T2+G-$ $T2-G-$ $T2-G+$ | - - - - | 2.5 4.0 5.0 11 | 10 10 10 25 | mA mA mA mA |
| I_L | Latching current | $V_D=12V; I_{GT}=0.1A$ | $T2+G+$ $T2+G-$ $T2-G-$ $T2-G+$ | - - - - | 3.2 16 4.0 5.5 | 30 40 30 40 | mA mA mA mA |
| I_H | Holding current | $V_D=12V; I_{GT}=0.1A$ | | - | 4.0 | 30 | mA |
| V_T | On-state voltage | $I_T=15A$ | | - | 1.4 | 1.65 | V |
| V_{GT} | Gate trigger voltage | $V_D=12V; I_T=0.1A$ | 0.25 | 0.7 0.4 | 1.5 - | V V | |
| | | $V_D=400V; I_T=0.1A; T_j=125^\circ C$ | | | | | |
| I_D | Off-state leakage current | $V_D=V_{DRM(max)}; T_j=125^\circ C$ | | - | 0.1 | 0.5 | mA |

Dynamic Characteristics

| | | | | | | |
|-----------|--|---|---|----|---|-----------|
| dV_D/dt | Critical rate of rise of Off-state voltage | $V_{DM}=67\% V_{DRM(max)}; T_j=125^\circ C$ Exponential wave form; gate open circuit | - | 50 | - | $V/\mu s$ |
| t_{gt} | Gate controlled turn-on time | $I_{TM}=16A; V_D=V_{DRM(max)}; I_G=0.1A;$ $dI_G/dt=5A/\mu s$ | - | 2 | - | μs |

HAOPIN MICROELECTRONICS CO., LTD.

Description

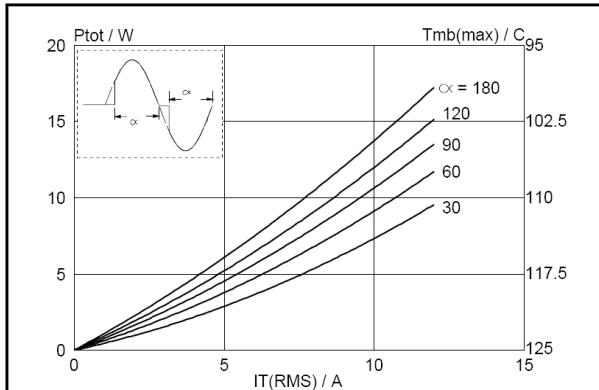


Fig. 1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where α = conduction angle.

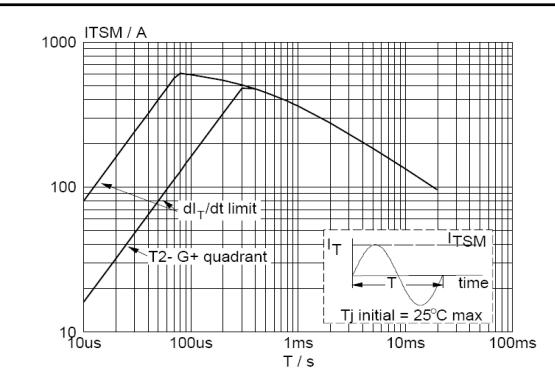


Fig. 2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \leq 20\text{ms}$.

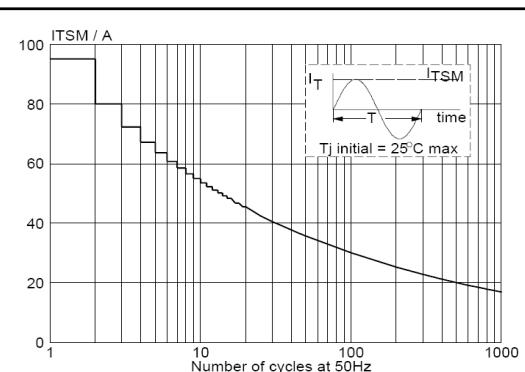


Fig. 3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, $f = 50\text{ Hz}$.

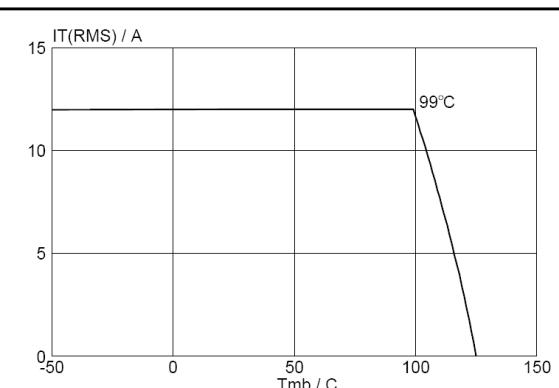


Fig. 4. Maximum permissible rms current $I_{T(RMS)}$, versus mounting base temperature T_{mb} .

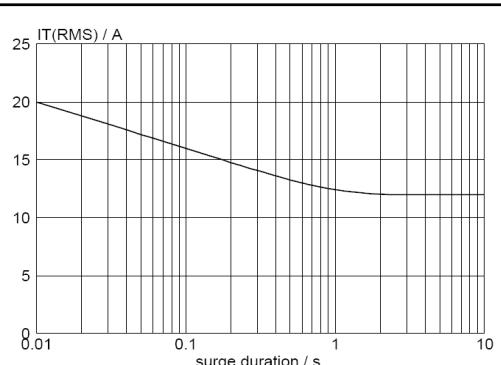


Fig. 5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, $f = 50\text{ Hz}$; $T_{mb} \leq 99^\circ\text{C}$.

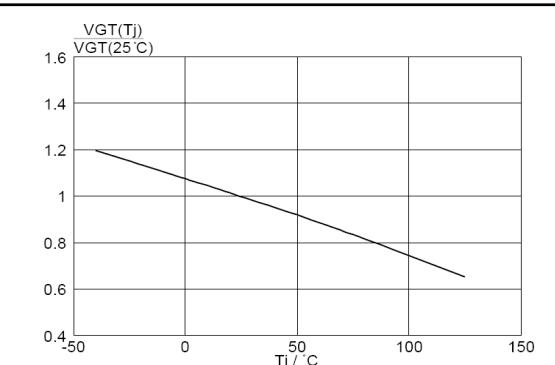


Fig. 6. Normalised gate trigger voltage $V_{GT}(T_j)/V_{GT}(25^\circ\text{C})$, versus junction temperature T_j .

Description

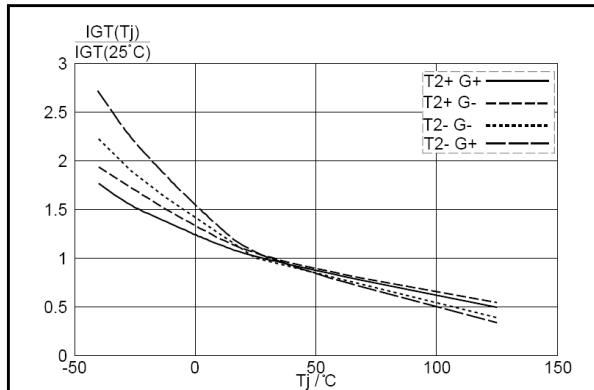


Fig.7. Normalised gate trigger current $I_{GT}(T_j)/I_{GT}(25^\circ\text{C})$, versus junction temperature T_j .

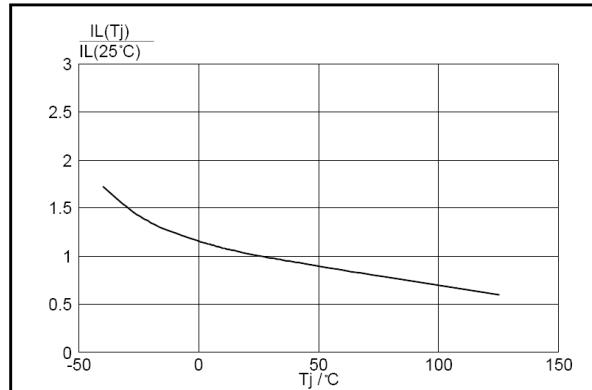


Fig.8. Normalised latching current $I_L(T_j)/I_L(25^\circ\text{C})$, versus junction temperature T_j .

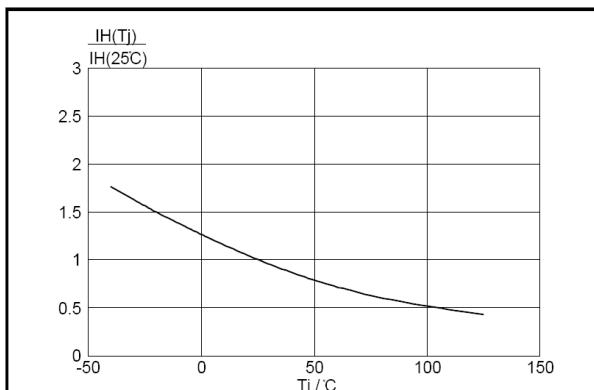


Fig.9. Normalised holding current $I_H(T_j)/I_H(25^\circ\text{C})$, versus junction temperature T_j .

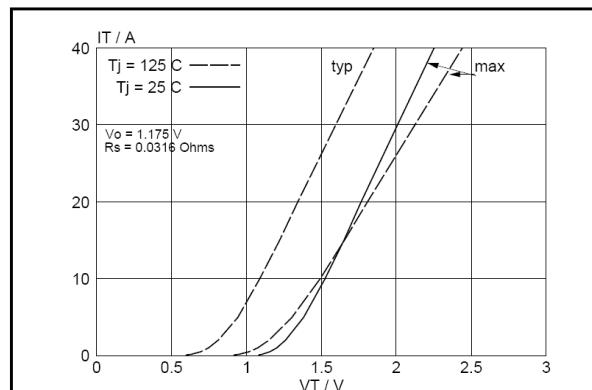


Fig.10. Typical and maximum on-state characteristic.

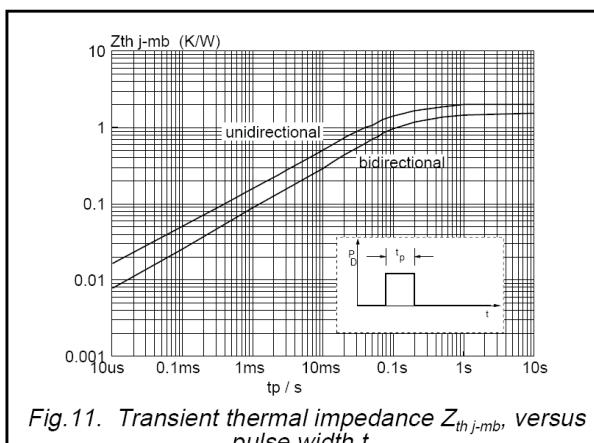


Fig.11. Transient thermal impedance $Z_{th,j-mb}$, versus pulse width t_p .

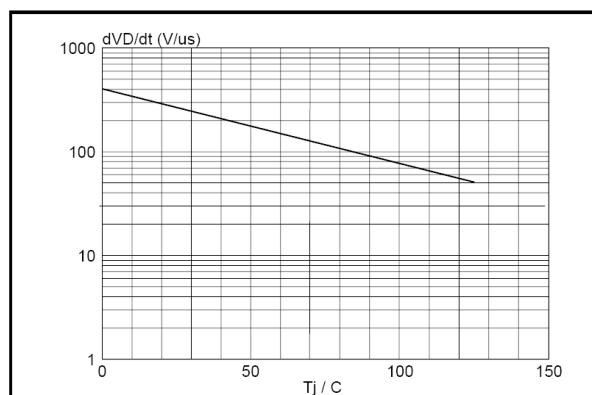


Fig.12. Typical, critical rate of rise of off-state voltage, dV_D/dt versus junction temperature T_j .

HAOPIN MICROELECTRONICS CO., LTD.

MECHANICAL DATA

Dimensions in mm

Net Mass: 2 g

TO-220

